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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (canceled)

Claim 2 (previously presented): A method for manufacturing a nonreciprocal circuit device comprising the steps of:
providing a permanent magnet;
providing a center-electrode assembly formed by the method according to Claim 5 to which a direct-current magnetic field is applied by the permanent magnet; and
providing a metallic case accommodating the permanent magnet and the center-electrode assembly.

Claim 3 (previously presented): A method for manufacturing a communication apparatus comprising the steps of:
providing a nonreciprocal circuit device formed by the method according to Claim 2; and
connecting at least one of a transmitting circuit and a reception circuit to the nonreciprocal circuit device.

Claim 4 (previously presented): A method for manufacturing a communication apparatus comprising the steps of:
providing a center-electrode assembly formed by the method according to Claim 5; and
connecting at least one of a transmission circuit and a reception circuit to the

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center-electrode assembly.

Claim 5 (previously presented): A method for manufacturing a center-electrode assembly comprising the steps of:

forming through-holes in a ferrite mother board;

alternately depositing a plurality of center-electrode patterns and a plurality of insulating films on the top surface of the ferrite mother board, the center-electrode patterns are formed by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method;

forming a conductive pattern on the back surface of the ferrite mother board by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method, and a conductive paste applying method;

cutting a center-electrode assembly from the ferrite mother board by cutting the ferrite mother board at intervals of a predetermined size; and

forming connecting electrodes in the through-holes in the center electrode assembly by at least one of a plating method, a printing method, a sputtering method, a vapor deposition method and a conductive paste applying method to electrically connect the center-electrode patterns formed on the top surface and the conductive pattern formed on the back surface; wherein

the plurality of center-electrode patterns and the plurality of insulating films are alternately deposited such that each of the plurality of center electrode patterns includes a portion that is in direct contact with a respective one of the plurality of insulating films and another portion that is in direct contact with the top surface of the ferrite mother board.

Claim 6 (previously presented): The method for manufacturing a center-electrode assembly according to claim 5, wherein the connecting electrodes are formed on grooves formed in the sides of the ferrite.

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Claim 7 (previously presented): The method for manufacturing a center-electrode assembly according to claim 5, further comprising the step of: forming ports directly on the sides of the ferrite; wherein the ports are electrically connected with the connecting electrodes via the plurality of center-electrode patterns.

Claim 8 (previously presented): The method for manufacturing a center-electrode assembly according to claim 7, further comprising the step of: forming gaps on the bottom surface of the ferrite; wherein the gaps are provided between ends of the ports and an end of the conductive pattern.

Claim 9 (previously presented): The method for manufacturing a center-electrode assembly according to claim 5, further comprising the step of: forming ports directly on the upper surface of the ferrite; wherein the ports are electrically connected with the connecting electrodes via the plurality of center-electrode patterns.

Claims 10 and 11 (canceled).

Claim 12 (currently amended): A nonreciprocal circuit device comprising: a permanent magnet; a center-electrode assembly according to Claim 4-15 to which a direct-current magnetic field is applied by the permanent magnet; and a metallic case accommodating the permanent magnet and the center-electrode assembly.

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Claim 13 (previously presented): A communication apparatus comprising a nonreciprocal circuit device according to Claim 12, and connected thereto, at least one of a transmitting circuit and a reception circuit.

Claim 14 (currently amended): A communication apparatus comprising a center-electrode assembly according to Claim 1415, and connected thereto, at least one of a transmission circuit and a reception circuit.

Claim 15 (currently amended): ~~A center-electrode assembly according to claim 14, wherein~~ A center-electrode assembly comprising:

a ferrite;
center-electrode patterns and insulating films disposed on the top surface of the ferrite;

a conductive pattern formed on the bottom surface of the ferrite; and
connecting electrodes directly formed on sides of the ferrite; wherein
the connecting electrodes electrically connect the center-electrode patterns and
the conductive pattern;

said connecting electrodes, said center-electrode pattern and said conductive
pattern are comprised of at least one of a plated conductive material, a printed
conductive material, a sputtered conductive material, a vapor deposited conductive
material, and an applied paste conductive material formed directly on the sides, on the
top surface and on the bottom surface, respectively, of the ferrite;

the center-electrode patterns and the insulating films are alternately disposed
such that each of the center electrode patterns includes a portion that is in direct contact
with a respective one of the insulating films and another portion that is in direct contact
with the top surface of the ferrite mother board; and

the connecting electrodes are formed on grooves formed in the sides of the ferrite.

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Claim 16 (currently amended): A center-electrode assembly according to claim 4-15, further comprising:

ports directly formed on the sides of the ferrite; wherein
the ports are electrically connected with the connecting electrodes via the center-electrode patterns.

Claim 17 (previously presented): A center-electrode assembly according to claim 16, further comprising:

gaps formed on the bottom surface of the ferrite; wherein
the gaps are provided between ends of the ports and an end of the conductive pattern.

Claim 18 (currently amended): A center-electrode assembly according to claim 4-15, further comprising:

ports directly formed on the upper surface of the ferrite; wherein
the ports are electrically connected with the connecting electrodes via the center-electrode patterns.